

AMENDMENTS TO THE CLAIMS

Claims 1-14. (Cancelled)

15. (Currently Amended) A plating bath precursor formulated for redox system electroless plating as in Claim 17, wherein the second metal ions are one or more metal ions selected from nickel, cobalt, gold, silver, copper, palladium, platinum, indium, tin, lead, antimony, cadmium, zinc, and iron ions.

16. (Currently Amended) A plating bath precursor formulated for redox system electroless plating as in Claim 15, wherein the concentration of ions of said first metal is at least 0.001 mole/liter.

17. (Currently Amended) A plating bath precursor, formulated for redox system electroless plating, comprising first metal ions which are substantially not deposited in plating and second metal ions which are deposited in plating, complex forming agent and stabilizer forming a the redox system, said plating bath precursor comprising one or more first metal ions selected from a tetravalent titanium ion (Ti^{4+}), a trivalent cobalt ion (Co^{3+}) and a tetravalent tin ion (Sn^{4+}), being stabilized against reduction and deposition of the second metal ions, and prior to using the first metal ions are reduced from said higher oxidation state to said lower oxidation state to thereby activate the plating bath.